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PLASUS PLASMA MONITOR TECHNICAL SURVEY	Form PLA-SUR-R1

This survey is aimed at helping us offer you the most optimal plasma monitoring solution. Please return this form to either your local sales contact or to info@angstromsciences.com

Company name:		Tel.:	
Contact name:		Email:	

Application specific requirements:

1. Application Type: **(Coating, Etching, Cleaning, Surface Treatment, Other)**	
1a. General Purpose: **(Process/Plasma Analysis, Process Optimization, Process Control, Quality Control, Endpoint Detection, Other)**	
1b. Application Type: **(PECVD – CCP/ICP, Etching – CCP/ICP, Sputtering, Atmospheric – Plasma Jet, DBD, Other)**	
2. General Process Details	
Process gas(es):	
Power supply capacity (kW):	
Coating(s) produced, Layer(s) etched, Surface(s) treated:	

2a. Sputtering Application Details:	#1	#2	#3	#4
Target material:				
Target size (width *x* length, cm):				
Reactive gas(es):				
Power mode (DC, p-DC, MF, RF):				

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	#1	#2	#3	#4
Power supply capacity (kW):				
Anticipated max cathode power (kW):				
Make (manufacturer):				
Geometry (planar or rotatable):				
Configuration (single or dual cathode)				
Magnetics (balanced or unbalanced)				
Quantity:				

Existing or planned provisions for reactive gas supply to the process area:

Gas injection hardware:	
Number of control sections per cathode:	

2b. PECVD (CCP/ICP) Application Details:	#1	#2	#3	#4
Frequency:				
Precursor(s):				
Substrate Bias:				
Substrate Size:				

2c. Etching (CCP/ICP) Application Details:	#1	#2	#3	#4
Frequency:				
Layer material(s):				
Substrate Material:				
Condition of Etch Stop (Endpoint):				

2d. Surface Treatment Application Details:	#1	#2	#3	#4

	Substrate:				

3. Pumping setup:

Process chamber volume (m^3):	
HV pumping capacity (L/s):	

4. Process monitoring setup:

No. of independent processes to be monitored:	
Do all processes run at the same time?	
Requested temporal resolution?	
Total no. of spectrometer channels (200-1100 nm):	

5. Sensor type required (tick appropriate):		**Quantity**	**Notes**
5a. External Mount Optics			
A. Ex-vacuum collimator optics – Straight only:			
B. Viewports Required (Pls Note Flange Size):			
5b. Internal Mount Optics			
C. In-vacuum collimator optics - Straight:			
D. In-vacuum collimator optics – Right Angle:			
E. In-vacuum collimator optics – Flange Mount:			

6. Optical feedthroughs:

Flange type and size:		
No. of optical feedthrough in flange:		

7. Length of the external optics cable:		m. (0.5m increments)	

Note: Keep cables as short as possible for better signal intensity

8. Length of the in-vacuum optics cable:		m. (0.5m increments)	
Note: Keep cables as short as possible for better signal intensity			

9. MFCs

Specify MFCs	tick		Size (sccm)	Calibration (e.g. N$_2$)	Quantity

10. MFC cable length (in m) and quantity of cables required:	
Note: Use of PLASUS systems requires dedicated cables from an EMICON to a MFC.	

System integration Requirements

11. Is software integration with an HMI required?	
12. Is optional PROFIBUS interface required?	
13. Is any other FIELDBUS interface required?	

14. Any further relevant process information that might be important for us to know: